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Optical Bonding

In-house Manufacturing

Cover glass

System solutions

OEM Solutions

Custom Display

Production
Custom designs
Installation

Mechanical design



SPECIFICATION FOR LCM Module

MODULE No:	ET028VG20-K
CUSTOMER:	

YOURITECH	INITIAL	DATE
PREPARED BY		
CHECKED BY		
APPROVED BY		

CUSTOMER	INITIAL	DATE
APPROVED BY		



Contents

1. Block Diagram	5
2. Outline dimension	6
3. Input terminal Pin Assignment	7
4. LCD Optical Characteristics	8
4.1 Optical specification	8
5. Electrical Characteristicss	11
5.1 Absolute Maximum Rating	11
5.2 DC Electrical Characteristics	11
5.3 LED Backlight Characteristics	12
6. AC Characteristics	14
6.1 Timings for DSI Video mode	14
6.2 Reset Input Timing	16
7. LCD Module Out-Going Quality Level	17
7.1 VISUAL & FUNCTION INSPECTION STANDARD	17
7.1.1 Inspection conditions	17
7.1.3 Sampling Plan	18
7.1.4 Criteria (Visual)	19
8. Reliability Test Result	25
9. Cautions and Handling Precautions	26
9.1 Handling and Operating the Module	26
9.2 Storage and Transportation	26



* Description

This is a color active matrix TFT (Thin Film Transistor) LCD (liquid crystal display) that uses amorphous silicon TFT as a switching device. This module is composed of a Transmissive type TFT-LCD Panel, driver circuit, back-light unit. The resolution of a 2.8 " TFT-LCD contains 240x320 pixels, and can display up to 262K colors.

* Features

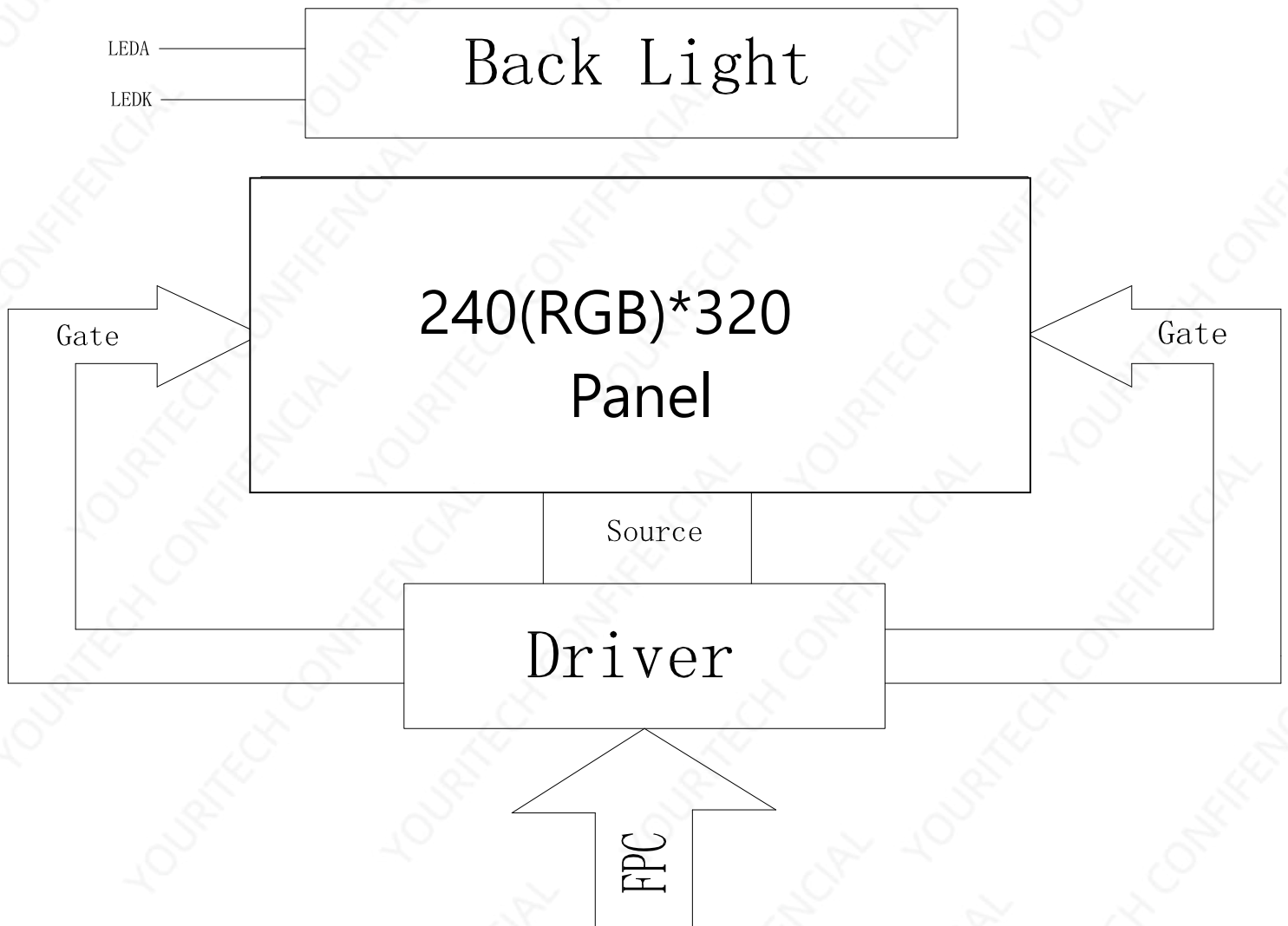
General Information Items	Specification	Unit	Note
	Main Panel		
Display area(AA)	43.20(H)*57.60(V) (2.8 inch)	mm	
Driver element	TFT active matrix	-	
Display colors	262K	colors	
Number of pixels	240(RGB)*320	dots	
Pixel arrangement	RGB vertical stripe	-	
Pixel pitch	0.18(H)*0.18(V)	mm	
Viewing angle	Free	o'clock	
Controller IC	JD9852	-	
LCM Interface	1-Lane MIPI	-	
Display mode	Transmissive /Normally Black	-	
Operating temperature	-20~+70	°C	
Storage temperature	-30~+80	°C	

* Mechanical Information

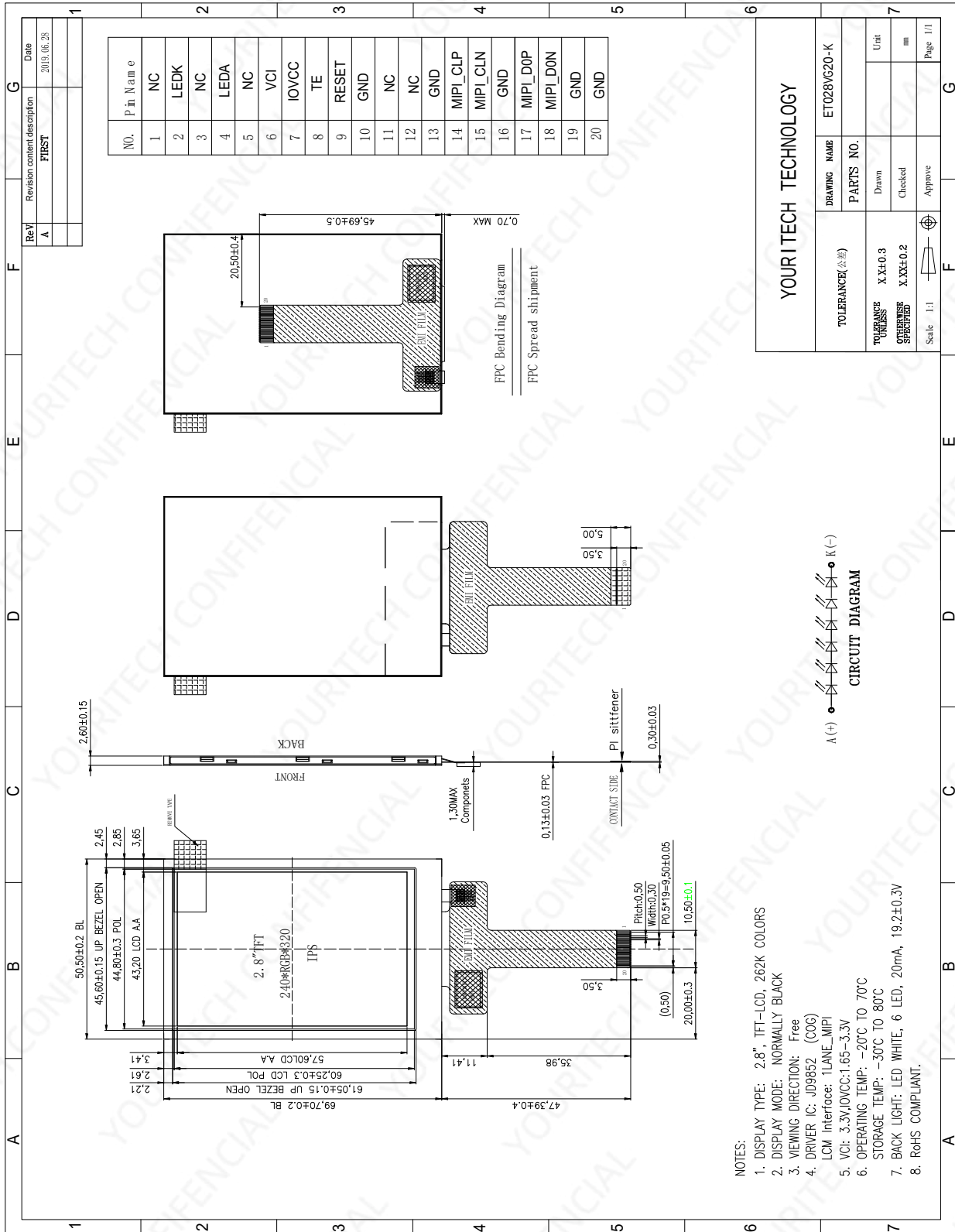
Item		Min.	Typ.	Max.	Unit	Note
Module size	Horizontal(H)	-	50.50	-	mm	
	Vertical(V)	-	69.70	-	mm	
	Depth(D)	-	2.60	-	mm	
Weight		-	20	-	g	



1. Block Diagram



2. Outline dimension



3. Input terminal Pin Assignment

Pin NO.	Symbol	Function	I/O
1	NC		
2	LEDK	Cathode pin of backlight.	P
3	NC		
4	LEDA	Anode pin of backlight.	P
5	NC		
6	VCI	Supply voltage (3.3V).	P
7	IOVCC	Power supply for I/O block(1.8-3.3V)	P
8	TE	Serve as a TE (Tearing Effect) output signal	O
9	RESET	Reset pin. Setting either pin low initializes the LSI. Must be reset after power is supplied.	I
10	GND	Ground.	P
11	NC		
12	NC		
13	GND	Ground.	P
14	MIPI_CLP	DSI Positive polarity of low voltage differential clock signal	I
15	MIPI_CLN	DSI Negative polarity of low voltage differential clock signal	
16	GND	Ground.	P
17	MIPI_D0P	DSI Positive polarity of low voltage differential data signal	I
18	MIPI_D0N	DSI Negative polarity of low voltage differential data signal	I
19	GND	Ground.	P
20	GND	Ground.	P



4. LCD Optical Characteristics

4.1 Optical specification

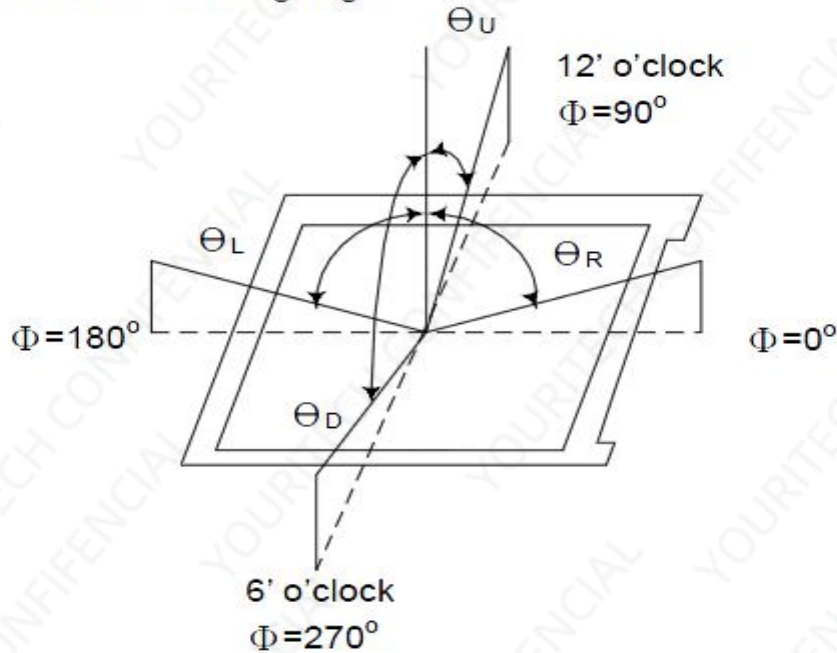
Item		Symbol	Condition	Min.	Typ.	Max.	Unit.	Note
Contrast Ratio		CR	$\Theta=0$ Normal viewing angle	600	800	--		(1)(2)
Response time	Rising	T_{R+T_F}		--	30	40	msec	(1)(3)
	Falling							
Color Gamut		S(%)		--	(60)	--	%	
Color Filter Chromaticity	White	W_X		0.2424	0.2824	0.3224		(1)(4) CF glass
		W_Y		0.2593	0.2993	0.3393		
	Red	R_X		0.5955	0.6155	0.6355		
		R_Y		0.3256	0.3454	0.3654		
	Green	G_X		0.2829	0.3029	0.3229		
		G_Y		0.5566	0.5766	0.5966		
	Blue	B_X		0.1288	0.1488	0.1688		
		B_Y		0.0372	0.0572	0.0772		
Viewing angle	Hor.	Θ_L	CR>10	--	80	--		(1)(4)
		Θ_R		--	80	--		
	Ver.	Θ_U		--	80	--		
		Θ_D		--	80	--		
Option View Direction		Free						

Measuring Condition

- Measuring surrounding: dark room
- Ambient temperature: $25\pm 2^\circ\text{C}$
- 15min. warm-up time.



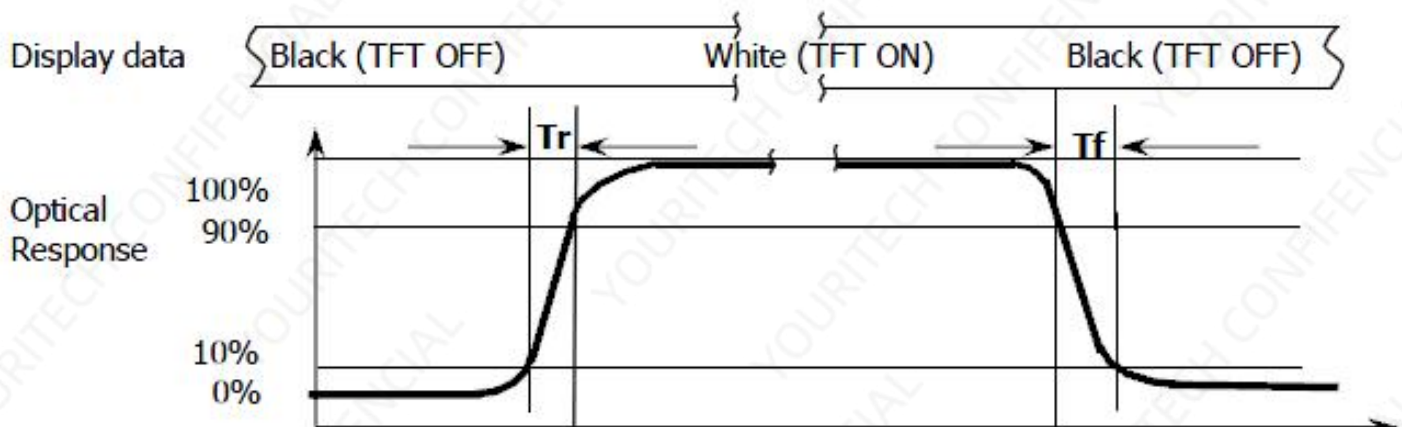
Note (1) Definition of Viewing Angle:



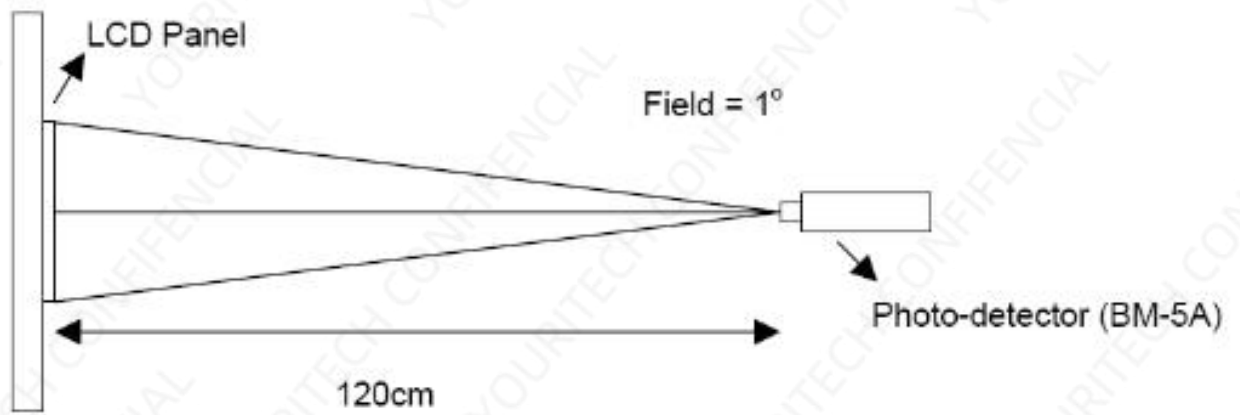
Note (2) Definition of Contrast Ratio (CR) :
measured at the center point of panel

$$CR = \frac{\text{Luminance with all pixels white}}{\text{Luminance with all pixels black}}$$

Note 3: Response Time



Note (4) Definition of optical measurement setup



5. Electrical Characteristics

5.1 Absolute Maximum Rating

Characteristics	Symbol	Min.	Max.	Unit	Note
Digital Supply Voltage	V _{CI}	-0.3	3.3	V	Note1
Digital interface supply Voltage	IOVCC	-0.3	3.3	V	Note1
Operating temperature	T _{OP}	-20	+70	°C	
Storage temperature	T _{ST}	-30	+80	°C	

NOTE1: If the absolute maximum rating of even is one of the above parameters is exceeded even momentarily, the quality of the product may be degraded. Absolute maximum ratings, therefore, specify the values exceeding which the product may be physically damaged. Be sure to use the product within the range of the absolute maximum ratings.

5.2 DC Electrical Characteristics

Characteristics	Symbol	Min.	Typ.	Max.	Unit	Note
Digital Supply Voltage	V _{CI}	2.6	3.3	3.6	V	
Digital interface supply Voltage	IOVCC	1.65	1.8	3.3	V	
Normal mode Current	I _{DD}	--	10	--	mA	
Level input voltage	V _{IH}	0.7*IOVCC	--	IOVCC+0.3	V	
	V _{IL}	GND-0.3	--	0.3*IOVCC	V	
Level output voltage	V _{OH}	IOVCC-0.4	--	--	V	
	V _{OL}	GND	--	GND+0.4	V	



5.3 LED Backlight Characteristics

The back-light system is edge-lighting type with 6 chips LED

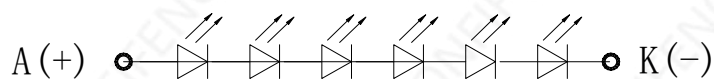
Item	Symbol	Min.	Typ.	Max.	Unit	Note
Forward Current	I_F	15	20	--	mA	
Forward Voltage	V_F	--	19.2	--	V	
LCM Luminance	LV	650	710	--	cd/m ²	Note3
LED life time	Hr	--	50000	--	Hour	Note1,2
Uniformity	Avg	80	--	--	%	Note3

Note1: LED life time (Hr) can be defined as the time in which it continues to operate under the condition:

$T_a=25\pm3\text{ }^{\circ}\text{C}$, typical IL value indicated in the above table until the brightness becomes less than 50%.

Note 2: The “LED life time” is defined as the module brightness decrease to 50% original brightness at

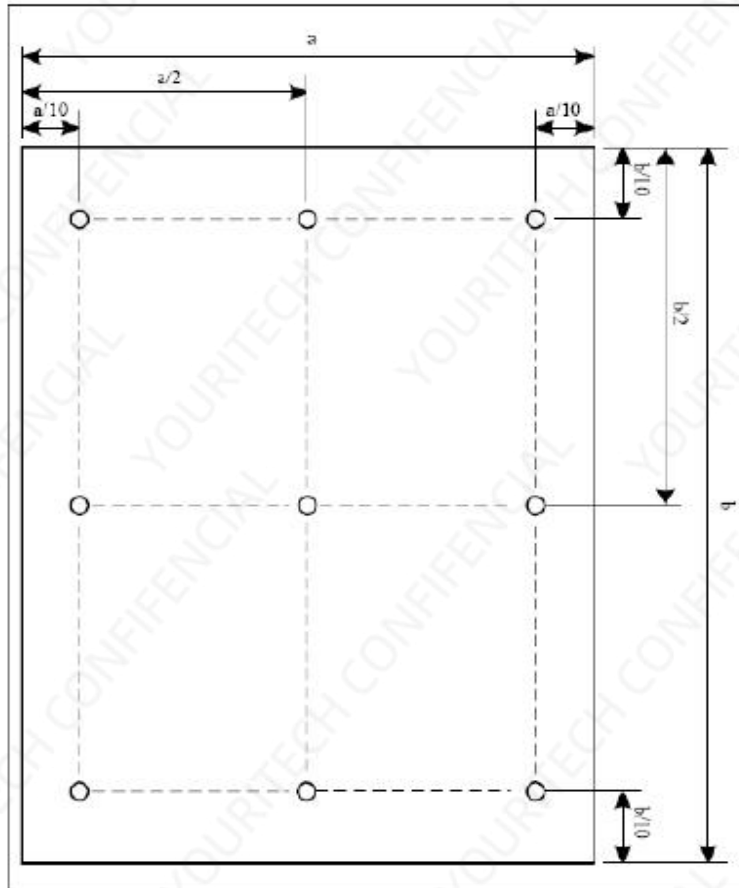
$T_a=25^{\circ}\text{C}$ and $IL=20\text{mA}$. The LED lifetime could be decreased if operating IL is larger than 20mA. The constant current driving method is suggested.



CIRCUIT DIAGRAM



Note (3) Luminance Uniformity of these 9 points is defined as below:



$$\text{Uniformity} = \frac{\text{minimum luminance in 9 points (1-9)}}{\text{maximum luminance in 9 points (1-9)}}$$

$$\text{Luminance} = \frac{\text{Total Luminance of 9 points}}{9}$$





Horizontal Timings

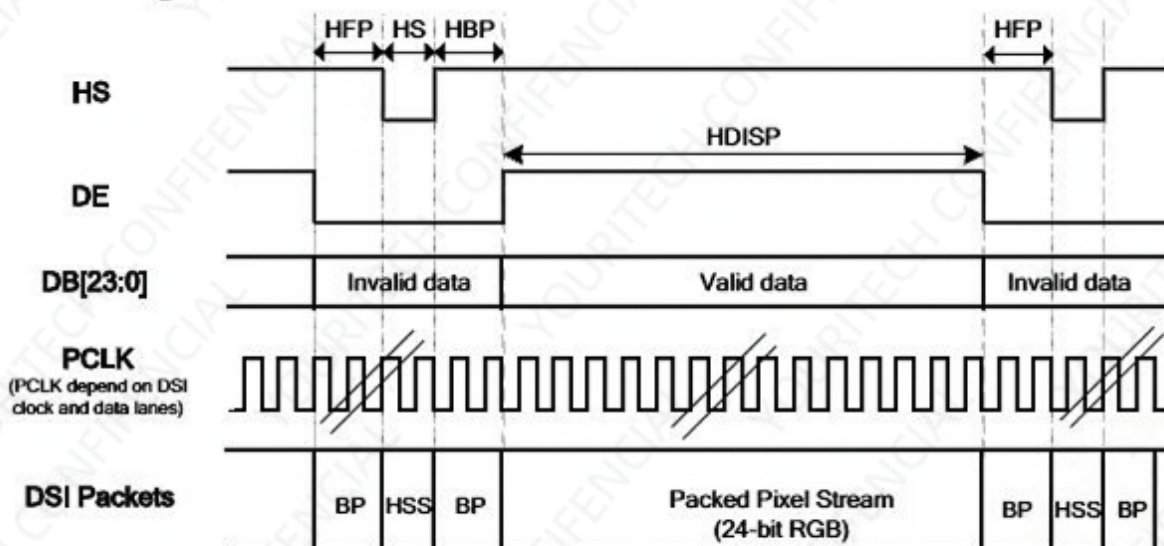


Figure. 10.13 Horizontal Timing for DSI Video mode I/F

Resolution=240x320 (TA=25°C, IOVCC=1.8V, VCI=2.8V)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
HS low pulse width	HS	-	6	-	78	DCK
Horizontal back porch	HBP	-	5	-	78	DCK
Horizontal front porch	HFP	-	5	-	78	DCK
Horizontal blanking period	HBLK	HS+HBP+HFP	16	-	88	DCK
Horizontal active area	HDISP	-	-	240	-	DCK

Note: (1) HS+HBP>0.5uS.

(2) HFP>0.5uS.

Table 10.11 Horizontal Timings for DSI Video mode I/F



6.2 Reset Input Timing

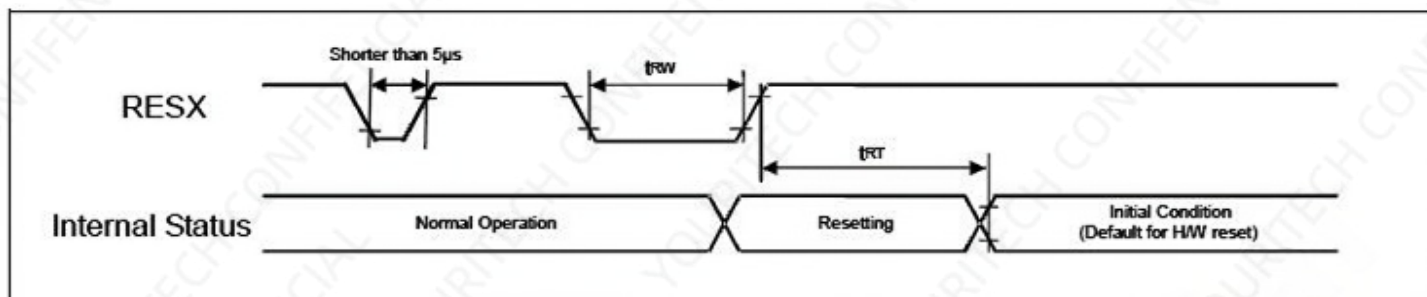


Figure. 10.5 Reset input timings

Symbol	Parameter	Related pins	Min.	Max.	Unit
t_{RW}	Reset pulse width ⁽²⁾	RESX	10	-	μs
t_{RT}	Reset complete time ⁽³⁾	-	-	5 (Note 5)	ms
		-	-	120 (Note 6, 7)	ms

Note: (1) The reset complete time also required time for loading ID bytes from OTP to registers. This loading is done every time when there is HW reset cancel time (t_{RT}) within 5 ms after a rising edge of RESX.

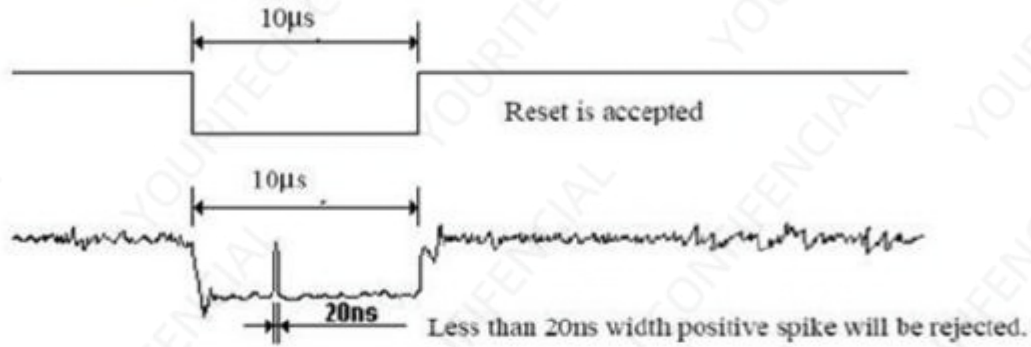
(2) Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 5 μs	Reset Rejected
Longer than 10 μs	Reset
Between 5 μs and 10 μs	Reset Start

(3) During the resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode) and then returns to Default condition for H/W reset.

(4) Spike Rejection also applies during a valid reset pulse as shown below:





(5) When Reset is applied during Sleep In Mode.

(6) When Reset is applied during Sleep Out Mode.

(7) It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.

7. LCD Module Out-Going Quality Level

7.1 VISUAL & FUNCTION INSPECTION STANDARD

7.1.1 Inspection conditions

Inspection performed under the following conditions is recommended.

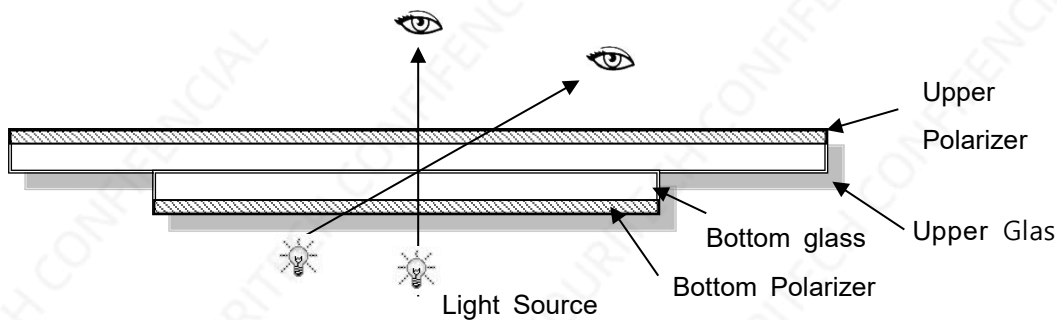
Temperature : $25\pm 5^{\circ}\text{C}$

Humidity : $65\%\pm 10\%\text{RH}$

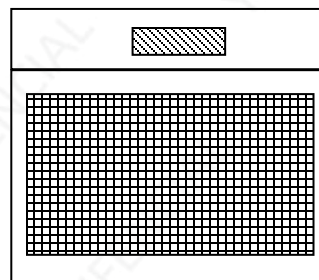
Viewing Angle : Normal viewing Angle.

Illumination: Single fluorescent lamp (300 to 700Lux)

Viewing distance: 30-50cm

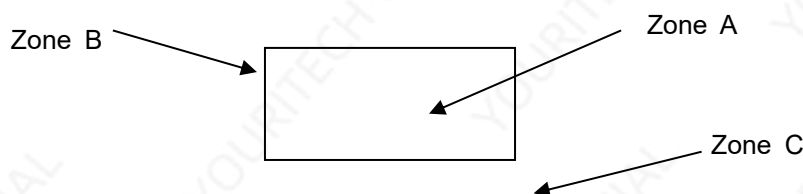


7.1.2 Definition



Zone D





Zone A : Effective Viewing Area(Character or Digit can be seen)

Zone B : Viewing Area except Zone A

Zone C : Outside (Zone A+Zone B) which can not be seen after assembly by customer .)

Zone D : IC Bonding Area

Note:As a general rule ,visual defects in Zone C can be ignored when it doesn't effect product function or appearance after assembly by customer

7.1.3 Sampling Plan

According to GB/T 2828.1-2003 ; , normal inspection, Class II

AQL:

Major defect	Minor defect
0.65	1.5

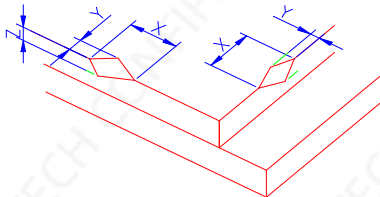
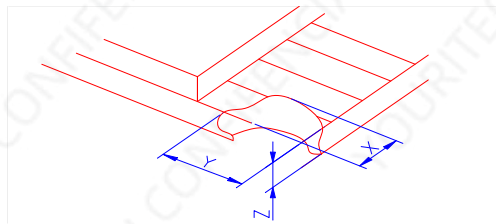
LCD: Liquid Crystal Display , TP: Touch Panel , LCM: Liquid Crystal Module

No	Items to be inspected	Criteria	Classification of defects
1	Functional defects	1) No display, Open or miss line 2) Display abnormally, Short 3) Backlight no lighting, abnormal lighting. 4) TP no function	Major
2	Missing	Missing component	
3	Outline dimension	Overall outline dimension beyond the drawing is not allowed	
4	Color tone	Color unevenness, refer to limited sample	Minor
5	Spot Line defect	Light dot, Dim spot,Polarizer Bubble ; Polarizer accidented spot.	

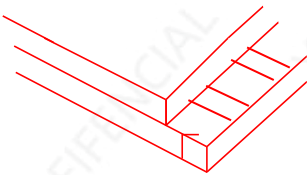


6	Soldering appearance	Good soldering , Peeling off is not allowed.	
7	LCD/Polarizer/TP	Black/White spot/line, scratch, crack, etc.	

7.1.4 Criteria (Visual)

Number	Items	Criteria(mm)						
1.0 LCD Crack/Broken NOTE: X: Length Y: Width Z: Height L: Length of IT O, T: Height of LCD	(1) The edge of LCD broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td><Inner border line of the seal</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	<Inner border line of the seal	≤T
X	Y	Z						
≤3.0mm	<Inner border line of the seal	≤T						
	(2)LCD corner broken	 <table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>≤3.0mm</td><td>≤L</td><td>≤T</td></tr></table>	X	Y	Z	≤3.0mm	≤L	≤T
X	Y	Z						
≤3.0mm	≤L	≤T						

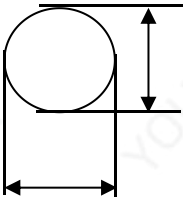


	(3) LCD crack	 Crack Not allowed
--	---------------	---



2.0

Spot defect



Φ=(X+Y)/2

① light dot (LCD/TP/Polarizer black/white spot , light dot, pinhole, dent, stain)

Zone Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.10	Ignore		
0.10<Φ≤0.20	3(distance ≥ 10mm)		
0.20<Φ≤0.25	2		
Φ>0.3	0		

②Dim spot (LCD/TP/Polarizer dim dot, light leakage、dark spot)

Zone Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.1	Ignore		
0.10<Φ≤0.20	3(distance ≥ 10mm)		
0.20<Φ≤0.25	2		
Φ>0.3	0		

③ Polarizer accidented spot

Zone Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		
0.3<Φ≤0.5	2(distance ≥ 10mm)		
Φ>0.5	0		

④Pixel bad points (light dot, Dim dot, color dot)

Zone Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.1	Ignore		
0.15<Φ≤0.2	2(distance ≥ 10mm)		
Φ>0.2	0		

⑤ Polarizer Bubble

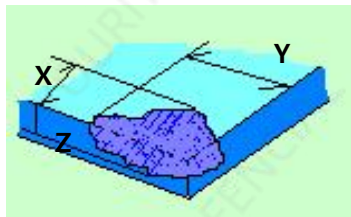
Zone Size (mm)	Acceptable Qty		
	A	B	C
Φ≤0.2	Ignore		
0.3<Φ≤0.4	3(distance ≥ 10m)		
0.5<Φ≤0.6	2		



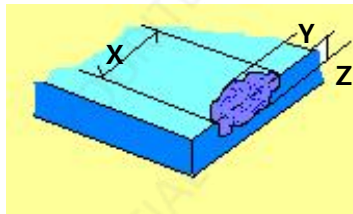
3.0	Line defect (LCD/TP /Polarizer backlight black/white line, scratch, stain)	Width(mm)	Length(m m)	Acceptable Qty		
				A	B	C
		$\Phi \leq 0.03$	Ignore	Ignore		Ignore
		$0.03 < W \leq 0.04$	$L \leq 3.0$	$N \leq 2$		
		$0.04 < W \leq 0.05$	$L \leq 2.0$	$N \leq 1$		
$0.05 < W$		Define as spot defect				
4.0	Electronic Components SMT	Not allow missing parts, solderless connection, cold solder joint, mismatch, The positive and negative polarity opposite				
5.0	Display color& Brightness	1. Color: Measuring the color coordinates, The measurement standard according to the datasheet or samples. 2. Brightness: Measuring the brightness of White screen, The measurement standard according to the datasheet or Samples.				
6.0	LCD Mura	By 5% ND filter invisible.				

7.0	CTP Related	CTP Cover sensor acc identified black/white spot				
			Size Φ (mm)	Acceptable Qty		
				A	B	C
			$\Phi \leq 0.1$	Ignore		Ignore
			$0.1 < \Phi \leq 0.2$	3 (distance $\geq 10\text{mm}$)		
			$0.20 < \Phi \leq 0.25$	2		
$\Phi > 0.3$	0					



CTP Cover scratch	Width(mm)	Ignore (mm)	Acceptable Qty								
			A	B	C						
	$\Phi \leq 0.03$	Ignore	Ignore								
	$0.03 < W \leq 0.04$	$L \leq 3.0$	$N \leq 2$								
	$0.04 < W \leq 0.05$	$L \leq 2.0$	$N \leq 1$								
	$0.05 < W$	Define as spot defect									
CTP Cover Pinhole/ Lack of ink	Zone Size (mm)		Acceptable Qty								
			C								
	$\Phi \leq 0.1$		Ignore								
	$0.1 < \Phi \leq 0.2$		3(distance $\geq 10\text{mm}$)								
	$0.2 < \Phi \leq 0.25$		2								
	$\Phi > 0.3$		0								
CTP Bonding bubble/ accident spot	Size $\Phi(\text{mm})$		Acceptable Qty								
			A		B						
	$\Phi \leq 0.1$		Ignore								
	$0.1 < \Phi \leq 0.15$		2(distance $\geq 10\text{mm}$)								
	$0.15 < \Phi \leq 0.2$		1								
	$\Phi > 0.2$		0								
Assembly deflection	beyond the edge of backlight $\leq 0.2\text{mm}$										
TP cover broken X : length Y : width Z : height	<table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>$X \leq 0.5\text{mm}$</td><td>$Y \leq 0.5\text{mm}$</td><td>$Z < \text{cover thickness}$</td></tr></table>			X	Y	Z	$X \leq 0.5\text{mm}$	$Y \leq 0.5\text{mm}$	$Z < \text{cover thickness}$		
	X	Y	Z								
$X \leq 0.5\text{mm}$	$Y \leq 0.5\text{mm}$	$Z < \text{cover thickness}$									
* Circuitry broken is not allowed.											



			<table><tr><td>X</td><td>Y</td><td>Z</td></tr><tr><td>$X \leq 0.3\text{mm}$</td><td>$Y \leq 0.3\text{mm}$</td><td>$Z < \text{LCD thickness}$</td></tr></table>	X	Y	Z	$X \leq 0.3\text{mm}$	$Y \leq 0.3\text{mm}$	$Z < \text{LCD thickness}$	
X	Y	Z								
$X \leq 0.3\text{mm}$	$Y \leq 0.3\text{mm}$	$Z < \text{LCD thickness}$								
		TP cover broken								
		X : length								
		Y : width								
		Z : height								
		* Circuitry broken is not allowed.								

Criteria (functional items)

Number	Items	Criteria (mm)
1	No display	Not allowed
2	Missing segment	Not allowed
3	Short	Not allowed
4	Backlight no lighting	Not allowed
5	TP no function	Not allowed



8. Reliability Test Result

Item	Condition	Inspection after test
High Temperature Operating	70°C,96H	Inspection after 2~4hours storage at room temperature, the sample shall be free from defects: 1.Air bubble in the LCD; 2.Non-display; 3.Missing segments/line; 4.Glass crack; 5.Current IDD is twice higher than initial value.
Low Temperature Operating	-20°C, 96HR	
High Temperature Storage	80°C, 96HR	
Low Temperature Storage	-30°C, 96HR	
High Temperature & High Humidity Operating	+60°C, 90% RH ,96 hours.	
Thermal Shock (Non-operation)	-30°C,30 min ↔ +80°C,30 min, Change time:5min 20CYC.	
ESD test	C=150pF, R=330,5points/panel Air:±8KV, 5times; Contact:±6KV, 5 times; (Environment: 15°C~35°C, 30%~60%).	
Vibration (Non-operation)	Frequency range:10~55Hz, Stroke:1.5mm Sweep:10Hz~55Hz~10Hz 2 hours for each direction of X.Y.Z. (6 hours for total) (Package condition).	
Box Drop Test	1 Corner 3 Edges 6 faces,80cm(MEDIUM BOX)	

Remark:

- 1.The test samples should be applied to only one test item.
- 2.Sample size for each test item is 5~10pcs.
- 3.For Damp Proof Test, Pure water(Resistance > 10MΩ) should be used.
- 4.In case of malfunction defect caused by ESD damage, if it would be recovered to normal state after resetting, it would be judged as a good part.
- 5.Failure Judgment Criterion: Basic Specification, Electrical Characteristic, Mechanical Characteristic, Optical Characteristic.



9. Cautions and Handling Precautions

9.1 Handling and Operating the Module

- (1) When the module is assembled, it should be attached to the system firmly.
Do not warp or twist the module during assembly work.
- (2) Protect the module from physical shock or any force. In addition to damage, this may cause improper operation or damage to the module and back-light unit.
- (3) Note that polarizer is very fragile and could be easily damaged. Do not press or scratch the surface.
- (4) Do not allow drops of water or chemicals to remain on the display surface.
If you have the droplets for a long time, staining and discoloration may occur.
- (5) If the surface of the polarizer is dirty, clean it using some absorbent cotton or soft cloth.
- (6) The desirable cleaners are water, IPA (Isopropyl Alcohol) or Hexane.
Do not use ketene type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanent damage to the polarizer due to chemical reaction.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contact with hands, legs, or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static; it may cause damage to the CMOS ICs.
- (9) Use finger-stalls with soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (10) Do not disassemble the module.
- (11) Protection film for polarizer on the module shall be slowly peeled off just before use so that the electrostatic charge can be minimized.
- (12) Pins of I/F connector shall not be touched directly with bare hands.
- (13) Do not connect, disconnect the module in the "Power ON" condition.

9.2 Storage and Transportation.

- (1) Do not leave the panel in high temperature, and high humidity for a long time.
It is highly recommended to store the module with temperature from 0 to 35 °C and relative humidity of less than 70%
- (2) Do not store the TFT-LCD module in direct sunlight.
- (3) The module shall be stored in a dark place. When storing the modules for a long time, be sure to adopt effective measures for protecting the modules from strong ultraviolet radiation, sunlight, or fluorescent light.
- (4) It is recommended that the modules should be stored under a condition where no condensation is allowed. Formation of dewdrops may cause an abnormal operation or a failure of the module.
In particular, the greatest possible care should be taken to prevent any module from being operated where condensation has occurred inside.
- (5) This panel has its circuitry FPC on the bottom side and should be handled carefully in order not to be stressed.